

SOT1220

plastic, thermal enhanced ultra thin small outline package;
no leads; 6 terminals; 0.65 mm pitch; 2 mm x 2 mm x 0.65
mm body

23 January 2017

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFN2020MD-6
Package type industry code	DFN2020MD-6
Package style descriptive code	HUSON (thermal enhanced ultra thin small outline; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	3-5-2012
Manufacturer package code	SOT1220

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.9	-	2	2.1	mm
E	package width	1.9	-	2	2.1	mm
A	seated height	0.65	-	-	-	mm
e	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	6	-	



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2. Package outline

DFN2020MD-6: plastic thermal enhanced ultra thin small outline package; no leads; 6 terminals; body 2 x 2 x 0.65 mm

SOT1220

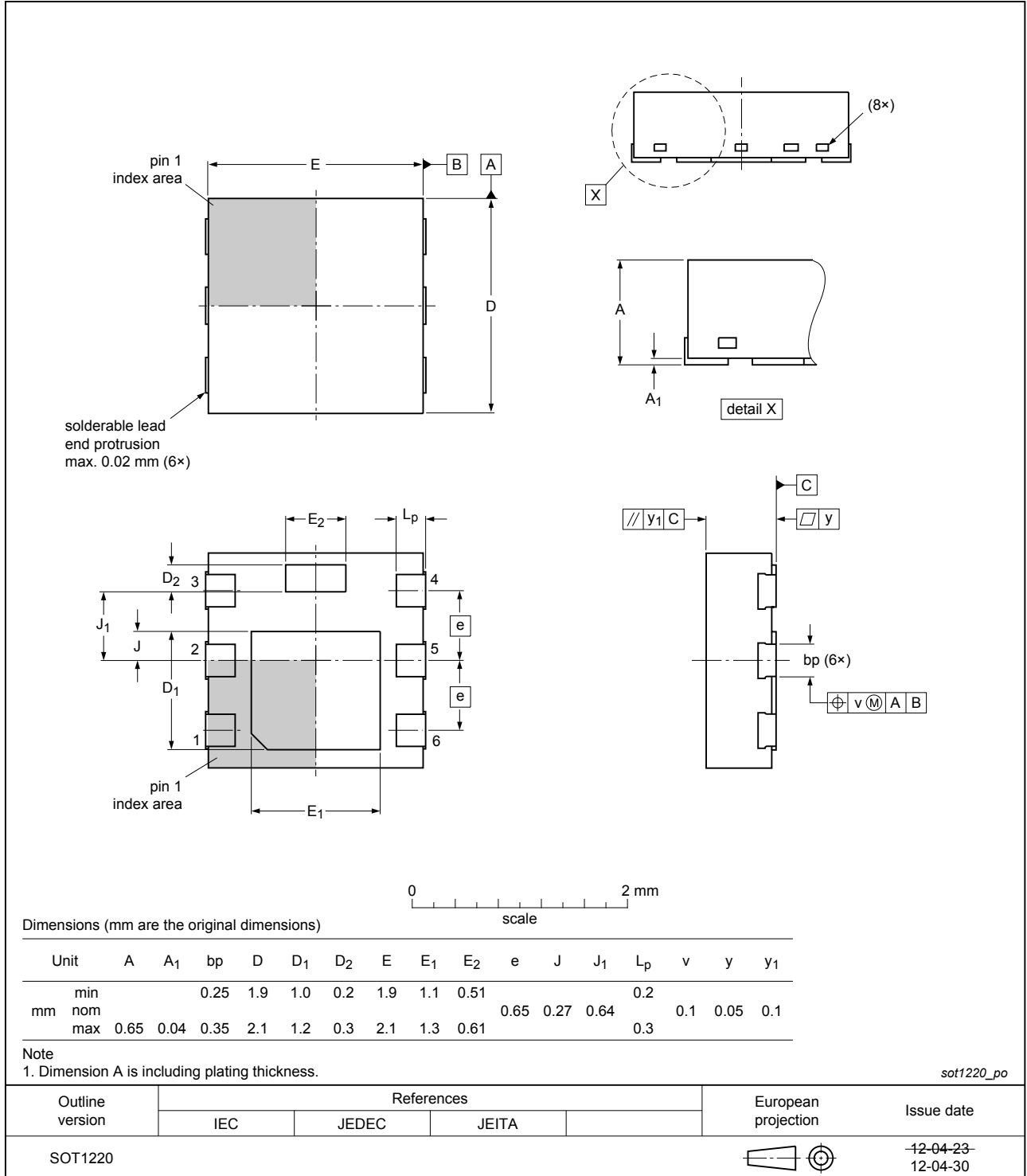


Fig. 1. Package outline DFN2020MD-6 (SOT1220)

plastic, thermal enhanced ultra thin small outline package; no leads; 6 terminals; 0.65 mm pitch; 2 mm x 2 mm x 0.65 mm body

3. Soldering

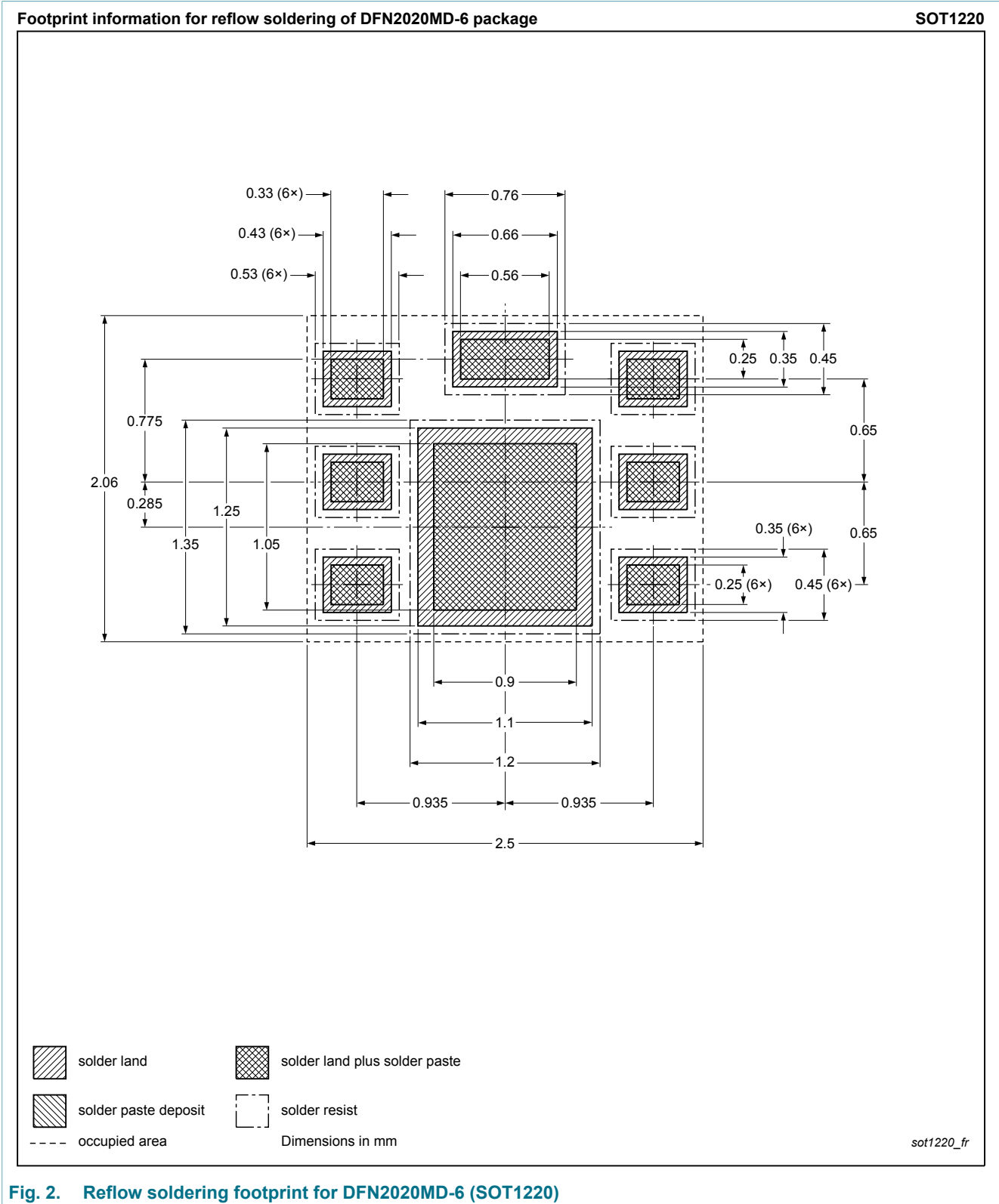


Fig. 2. Reflow soldering footprint for DFN2020MD-6 (SOT1220)

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4. Legal information

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